

Patent Abstracts of Japan

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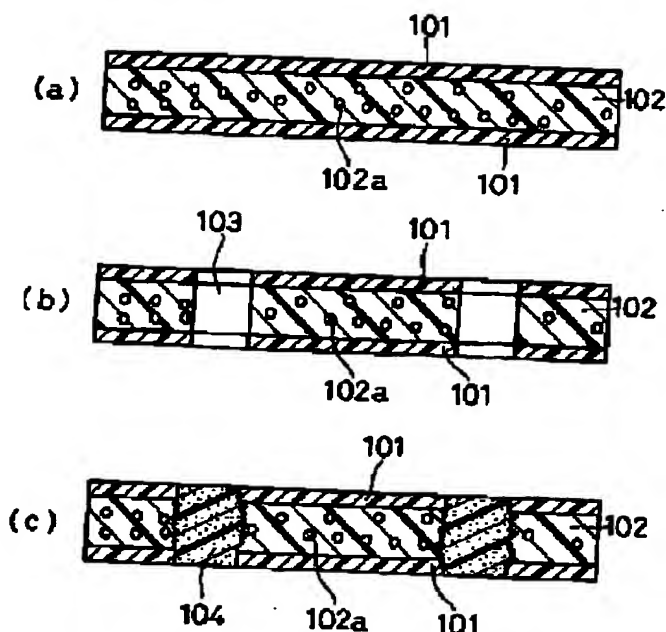
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TITLE : CIRCUIT SUBSTRATE CONNECTING
MATERIAL AND MANUFACTURE OF
MULTILAYER CIRCUIT SUBSTRATE
USING IT



ABSTRACT : PURPOSE: To make it possible to connect inner via holes, and to accomplish a highly reliable and high quality circuit substrate connecting material and an electric connector by a method wherein a mold-releasing film is provided on both surfaces of an organic porous substrate, a through hole is provided on the desired position, and a conductive resin composition is filled up to the surface of the mold-releasing film.

CONSTITUTION: Holes are formed on an organic porous substrate 102 on which a mold-releasing film 101 is provided on both surfaces, and a multilayer substrate is formed easily from a double-sided plate, which can be stably formed relatively, and a four-layer substrate by using a circuit substrate connecting material having the structure in which conductive paste is embedded up to the surface of the mold-releasing film. By filling up the conductive paste 104 up to the surface of the mold-releasing film 101, the conductive paste 104 jumps out protrusively from the surface of the organic porous substrate 102 after the mold-releasing film 101 has been peeled off, and as a result, the filling quantity of the conductive material after lamination can be increased, and connection resistance becomes very small.

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